IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Kelly T. Hurley

Serial No.:

Filed: February 26, 2004

Mail Stop Patent Application

Alexandria, VA 22313-1450

Commissioner for Patents

For: OPTIMIZED FLASH MEMORY CELL

Group Art Unit:

Examiner:

Atty. Docket: 2000-0116.01/US

999999999 Paper No.

INFORMATION DISCLOSURE STATEMENT

Certificate of Express Mailing (37 CFR § 1.10)

'Express Mail" mail label number: ET658403150US

Date of Deposit: February 25, 2004

I hereby certify that this paper is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR §1.10 on the date indicated above and is addressed to the Commissioner for Patents, P. Q Box 1450, Alexandria, VA 22313-1450.

Dear Sir:

P.O. Box 1450

In compliance with the duty of disclosure under 37 C.F.R. § 1.56, Applicant respectfully requests that this Information Disclosure Statement be entered and that the references listed on the attached Form PTO-1449 be considered by the Examiner and made of record. Copies of the listed references are enclosed for the convenience of the Examiner.

In accordance with 37 C.F.R. § 1.97(g), this Information Disclosure Statement is not to be construed as a representation that a search has been made or that no other possible material information as defined in 37 C.F.R. § 1.56(a) exists.

The following references are submitted for the Examiner's review:

U.S. Patents

U.S. Patent No.	Issue Date	<u>Inventor</u>
6,271,087	08/07/2001	Kinoshita et al.
6,188,115	02/13/2001	Kamitani
6,080,624	06/27/2000	Kamiya et al.
5,994,733	11/30/1999	Nishioka et al.
5,731,242	03/24/1998	Parat et al.
5,210,047	05/11/1993	Woo et al.

Other References

"A 130-mm², 256-Mbit NAND Flash with Shallow Trench Isolation Technology", Kenichi Imamiya et al.,

IEEE Journal of Solid-State Circuits, Vol. 34, No. 11, November 1999

"Novel 0.44µm2 Ti-Salicide STI Cell Technology for High Density NOR Flash Memories and High

Performance Embedded Application", H. Watanabe et al., IEDM 98, pp. 975-978

As this information is being submitted within three months of the date of filing of the application, Applicant

understands that no fee or certification is required for the submission and consideration of this information at this time.

If there are any matters which may be resolved or clarified through telephone interview, the Examiner is

respectfully requested to contact Applicant's undersigned attorney at the number indicated.

A Form PTO-1449 is enclosed herewith.

Date: 02/26/2004

Respectfully submitted,

David J. Paul

Reg. No. 34,692

Micron Technology, Inc.

8000 S. Federal Way

Boise, ID 83706-9632

(208) 368-4515

AGENT FOR APPLICANT

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FORM: PTO			Atty Docket No:	Serial No:				
(REV: 7-80)		PATENT AND TRADEMARK OFFICE		2000-0116.01/US				
					Applicant:			
INFORMATION DISCLOSURE STATEMENT BY APPLICANT		Kelly T. Hurley						
			Filing Date:	Group:				
(37 CFR 1.98(b)) (use several sheet		sheets if necessary)	February 26, 2004					
U.S. PATENT DOCUMENTS								
Examiner		Document	.		~ 1	~		
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	AA AB	6,271,087	08/07/2001	Kinoshita et al.	438	258		
	AC	6,188,115 6,080,624	02/13/2001 06/27/2000	Kamitani Kamitani	257	412		
-	AD	5,994,733	11/30/1999	Kamiya et al. Nishioka et al.	438	257 316		
	AE	5,731,242	03/24/1998	Parat et al.	438	586		
	AF	5,210,047	05/11/1993	Woo et al.	437	43		
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP §609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication with applicant.